

**AMENDMENTS TO THE CLAIMS**

1. (Original) A method of controlling the burning in of at least one I/C chip in a burn in tool, wherein said tool has a device for mounting each chip to be burned in, a power source to supply electrical current to burn in each chip, and a monitor to continuously monitor the temperature value of each chip, comprising the steps of:

continuously monitoring at least one electrical value input to each chip selected from the group of current, voltage and power, and varying the voltage to maintain at least one of the values at or below a given value.

2. (Original) The method of claim 1 wherein the voltage is varied to maintain the current value below a given value.

3. (Original) The method of claim 1 wherein the voltage is varied to maintain the power value below a given value.

4. (Original) The method of claim 1 wherein each device temperature is monitored and the voltage to each device is varied to maintain the device at a given temperature.

5. (Original) The method of claim 1 where there is a heat sink in contact with the device.

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6. (Original) The method of claim 5 wherein the device temperature of each device is monitored and the temperature of the heat sink is varied to maintain the device temperature at a given value.

7. (Original) A burn in tool for burning in at least one I/C chip comprising:  
a structure for mounting each chip to be burned in;  
a power source to supply electrical current to burn in each chip;  
a structure for continuously monitoring at least one electrical value input to each chip selected from the group of current, voltage and power, and  
a structure to vary the voltage to maintain at least one of the values at or below a given value.

8. (Original) The tool of claim 7 wherein the voltage is varied to maintain the current value below a given value.

9 (Original) The tool of claim 5 wherein the voltage is varied to maintain the power value below a given value.

10. (Original) The tool of claim 7 including a monitor to continuously monitor the temperature value of each chip being burned in and wherein the voltage is varied to maintain the temperature value of each device at a given value.

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11. (Previously presented) The tool of claim 7 wherein a heat sink is in contact with each device.

12. (Original) The tool of claim 7 wherein the tool has a heat sink and temperature monitor for each device and each heat sink has means to control the temperature of the heat sink, and the temperature control means is varied to maintain the temperature value of each device at a given value.